MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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IMAGE SENSOR MODULE A4
CASE MODAB
ISSUE C

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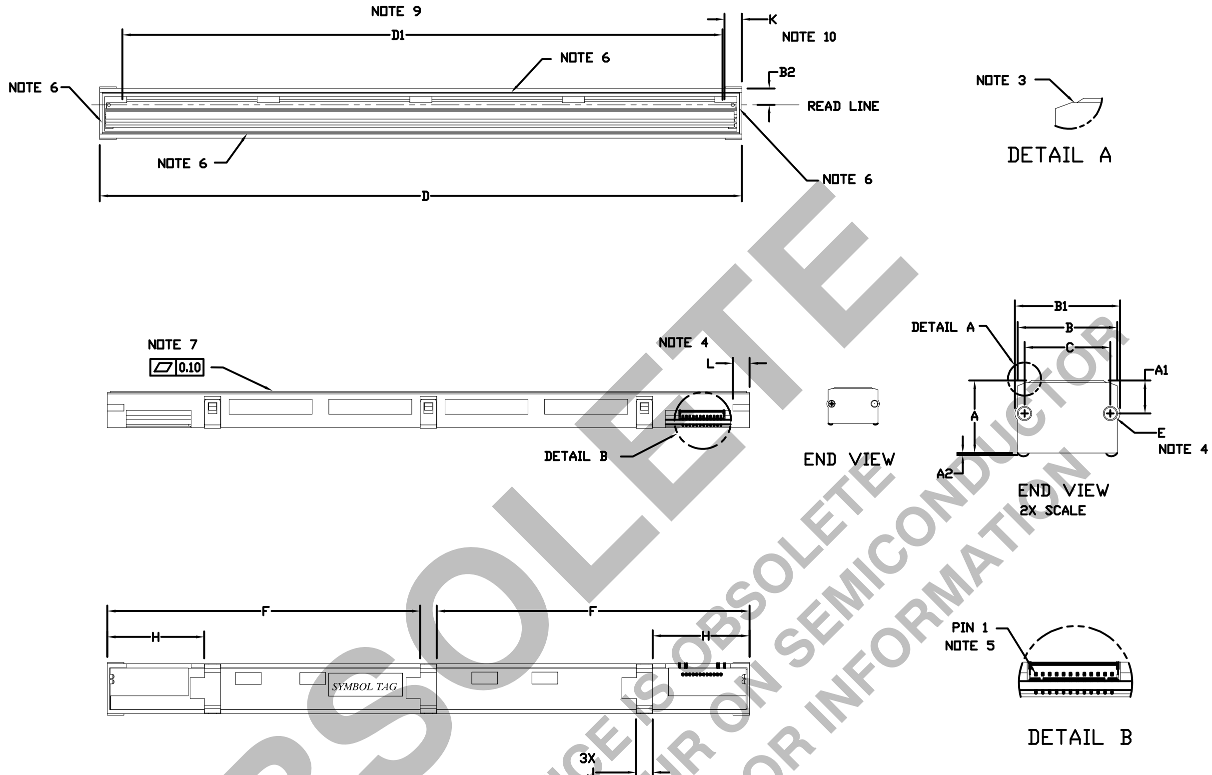

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NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING.
4. BORE DEPTH IS 6.0 WITH A 0.2 LEAD−IN CHAMFER.
5. CONNECTOR ASSEMBLY; MOLEX 53048−1210, 1 X 12 PIN, PITCH 1.25.
6. GLASS IS GLUED ON ALL 4 SIDES.
7. GLASS THICKNESS IS 1.85.
8. USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF−CM AND 2.00 KGF−CM.
9. DIMENSION D1 DENOTES THE SCAN LENGTH.
10. DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

	MILLIMETERS	
DIM	MIN	MAX
A	12.60	13.60
A1	5.45	6.45
A2	0.58 REF	
B	17.70	18.30
B1	18.70	19.30
B2	5.50	6.50
C	15.30	15.70
D	231.50	232.50
D1	216.00 REF	
E	2.15	2.25
F	112.50	113.50
H	34.50	35.50
J	5.70	6.30
K	5.30	7.30
L	6.00 REF	

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**IMAGE SENSOR MODULE A4**	**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY D. TRUHITTE.	09 DEC 2009
A	MAJOR REVISION OF DRAWING. REQ. BY D. TRUHITTE.	19 FEB 2010
B	REVISED DIMENSIONS A2 AND E. REQ. BY D. TRUHITTE.	31 MAR 2015
C	OBSOLETED.	17 DEC 2019

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